



## ■ Features

- Low power losses, high efficiency
- Low forward voltage drop, low reverse current
- Compliant with RoHS requirements, lead-free, halogen-free
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

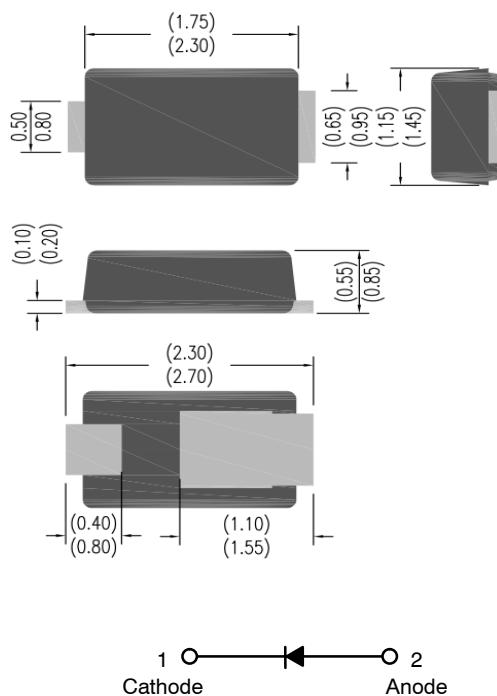
## ■ MECHANICAL DATA

- Package: SOD-323HE
- Terminals: Tin plated leads, solderable per
- Polarity: Cathode line denotes the cathode end

## ■ APPLICATIONS

- DC/DC converters

SOD-323HE



## ■ ABSOLUTE MAXIMUM RATINGS ( $T_a=25^\circ\text{C}$ )

PARAMETER	SYMBOL	LIMITS	UNIT
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	40	V
Maximum Average Rectified Forward Current	$I_o$	1.0	A
Peak Forward Surge Current (Half Sine Wave, 1 cycle, non-repetitive)	$I_{FSM}$	22	A
Operating Junction Temperature Range	$T_{JW}$	-40 to +150	°C
Storage Temperature Range	$T_{STG}$	-40 to +150	°C

## ■ ELECTRICAL CHARACTERISTICS ( $T_a=25^\circ\text{C}$ )

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Forward Voltage	$V_F1$	$I_F=0.7\text{A}$	-	0.48	-	V
	$V_F2$	$I_F=1.0\text{A}$	-	0.53	0.58	V
Reverse Current	$I_R1$	$V_R=5\text{V}$	-	0.5	-	µA
	$I_R2$	$V_R=40\text{V}$	-	-	100	µA
Typical Thermal Resistance Note1 Note2	$R_{\theta JA}$	Junction to Ambient	-	-	220 250	°C/W
Typical Thermal Resistance Note1	$R_{\theta JL}$	Junction to Lead	-	-	50	°C/W

Note : 1. Mounted on P.C Board with (15mm x 50mm) copper pad areas.

2. Mounted on a FR4 PCB, single-sided copper, mini pad.

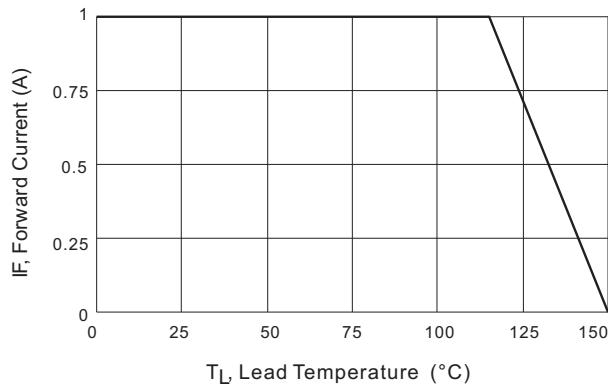


Fig.1 Forward Current Derating Curve

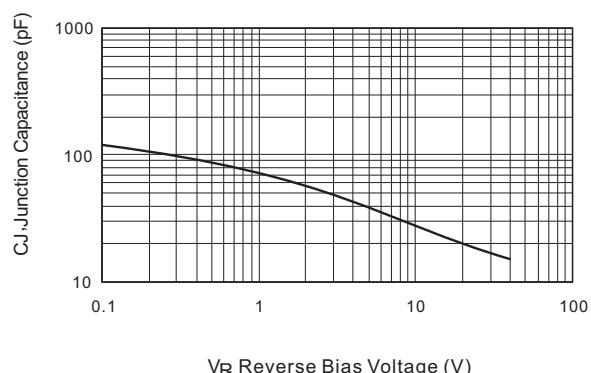


Fig.2 Typical Junction Capacitance

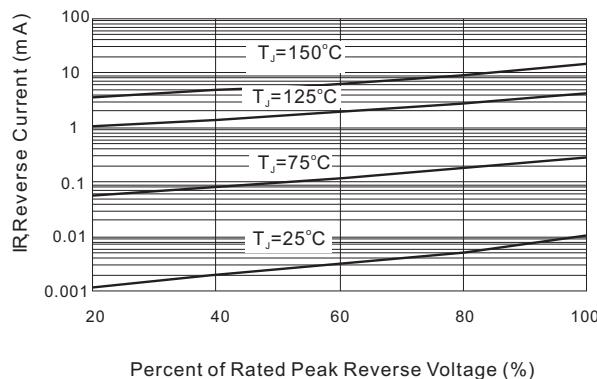


Fig.3 Typical Reverse Characteristics

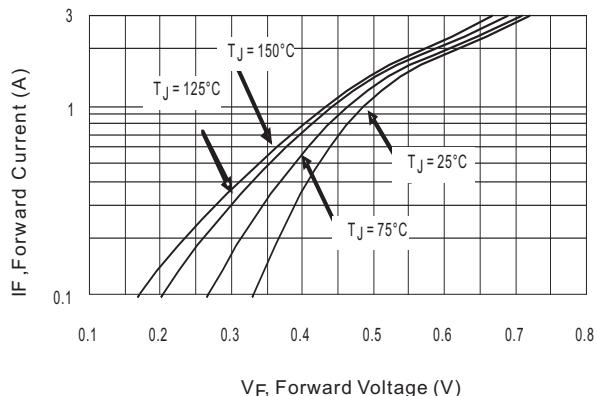


Fig.4 Typical Forward Characteristics

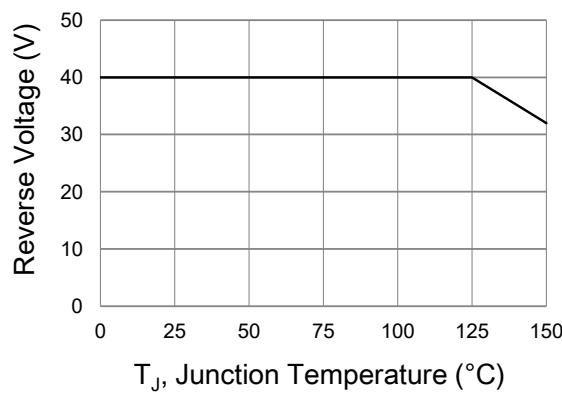


Fig.5 Operating Temperature Derating Curve